

Assistance on August 20, 2007, applicable to workers of Horizon Dental Lab, LLC, Rochester, New York. The notice was published in the **Federal Register** on September 11, 2007 (72 FR 51844).

At the request of the State agency, the Department reviewed the certification for workers of the subject firm. The workers are engaged in the production of dental prosthesis.

Information provided by the company shows that the correct name of the subject firm should read Horizon Dental Lab, LLC, also know as Q Dental Group PC. Workers separated from employment at the subject firm had their wages reported under the unemployment insurance (UI) tax account for Q Dental Group PC.

Accordingly, the Department is amending this certification to correctly identify the name of the subject firm.

The intent of the Department's certification is to include all workers of Horizon Dental Lab, LLC, Rochester, New York who were adversely affected by increased imports of dental prosthesis.

The amended notice applicable to TA-W-61,955 is hereby issued as follows:

"All workers of Horizon Dental Lab, LLC, also known as Q Dental Group PC, Rochester, New York, who became totally or partially separated from employment on or after August 1, 2006, through August 20, 2009, are

eligible to apply for adjustment assistance under Section 223 of the Trade Act of 1974, and are also eligible to apply for alternative trade adjustment assistance under Section 246 of the Trade Act of 1974."

Signed at Washington, DC, this 25th day of September 2007.

Linda G. Poole,
Certifying Officer, Division of Trade Adjustment Assistance.

[FR Doc. E7-19477 Filed 10-2-07; 8:45 am]

BILLING CODE 4510-FN-P

DEPARTMENT OF LABOR

Employment and Training Administration

Investigations Regarding Certifications of Eligibility To Apply for Worker Adjustment Assistance and Alternative Trade Adjustment Assistance

Petitions have been filed with the Secretary of Labor under Section 221(a) of the Trade Act of 1974 ("the Act") and are identified in the Appendix to this notice. Upon receipt of these petitions, the Director of the Division of Trade Adjustment Assistance, Employment and Training Administration, has instituted investigations pursuant to Section 221(a) of the Act.

The purpose of each of the investigations is to determine whether the workers are eligible to apply for

adjustment assistance under Title II, Chapter 2, of the Act. The investigations will further relate, as appropriate, to the determination of the date on which total or partial separations began or threatened to begin and the subdivision of the firm involved.

The petitioners or any other persons showing a substantial interest in the subject matter of the investigations may request a public hearing, provided such request is filed in writing with the Director, Division of Trade Adjustment Assistance, at the address shown below, not later than October 15, 2007.

Interested persons are invited to submit written comments regarding the subject matter of the investigations to the Director, Division of Trade Adjustment Assistance, at the address shown below, not later than October 15, 2007.

The petitions filed in this case are available for inspection at the Office of the Director, Division of Trade Adjustment Assistance, Employment and Training Administration, U.S. Department of Labor, Room C-5311, 200 Constitution Avenue, NW., Washington, DC 20210.

Signed at Washington, DC, this 25th day of September 2007.

Ralph DiBattista,
Director, Division of Trade Adjustment Assistance.

APPENDIX—TAA

[Petitions instituted between 9/17/07 and 9/21/07]

TA—W	Subject Firm (petitioners)	Location	Date of institution	Date of petition
62147	Information Systems Network (Comp)	Buckhead, GA	09/17/07	09/14/07
62148	Unicare Insurance Co. (Wkrs)	Bolingbrook, IL	09/17/07	09/13/07
62149	Aptara (Comp)	York, PA	09/17/07	09/13/07
62150	Qiagen (State)	Plymouth, MN	09/17/07	09/14/07
62151	Johnson Controls (Wkrs)	Plymouth, MI	09/17/07	09/14/07
62152	Interlock Industries (Wkrs)	Nile, OH	09/17/07	09/10/07
62153	ITT Marine and Leisure (State)	Santa Ana, CA	09/18/07	09/17/07
62154	Taylor Togs, Inc. (Comp)	Taylorsville, NC	09/18/07	09/17/07
62155	Daws Manufacturing Co., Inc. (Comp)	Pensacola, FL	09/18/07	09/04/07
62156	Hypercom (State)	Phoenix, AZ	09/18/07	09/14/07
62157	Johnston Textiles, Inc. (Comp)	Opp, AL	09/18/07	09/17/07
62158	Intel (Wkrs)	Rio Rancho, NM	09/18/07	09/10/07
62159	Chicago Miniature Lighting (State)	Hackensack, NJ	09/19/07	08/27/07
62160	Data Products USA (State)	Clexico, CA	09/19/07	09/12/07
62161	Tifton Aluminum Company (Comp)	Tifton, GA	09/19/07	09/18/07
62162	Barn Door Furniture Company (The) (Comp)	Henderson, NC	09/19/07	09/18/07
62163	Smart Novelty Blouse Co., Inc. (Wkrs)	New York, NY	09/19/07	09/17/07
62164	Huntleigh Healthcare, LLC (Comp)	Eatontown, NJ	09/19/07	09/18/07
62165	Omni Futon (Wkrs)	Spring Green, WI	09/19/07	09/13/07
62166	Thompson Scientific (State)	Cherry Hill, NJ	09/19/07	09/18/07
62167	Dura Automotive Systems, Inc. (Comp)	Jacksonville, FL	09/19/07	09/10/07
62168	Sensata Technologies (Comp)	Standish, ME	09/19/07	09/17/07
62169	Flexaust Company, Inc. (Comp)	El Paso, TX	09/20/07	09/14/07
62170	United Machine Works, Inc. (Wkrs)	Greenville, NC	09/20/07	09/12/07
62171	Everett Charles Technologies (Wkrs)	Clifton Park, NY	09/20/07	09/11/07
62172	Carhartt Inc. (Comp)	Galesburg, IL	09/20/07	09/19/07
62173	United Memorial Bible Services (Wkrs)	Gastonia, NC	09/20/07	09/19/07
62174	Penn Union Corporation (Comp)	Edinboro, PA	09/20/07	09/12/07

APPENDIX—TAA—Continued
[Petitions instituted between 9/17/07 and 9/21/07]

TA—W	Subject Firm (petitioners)	Location	Date of institution	Date of petition
62175	Masys Corporation (Comp)	Minneapolis, MN	09/20/07	09/14/07
62176	First American Corporation (Wkrs)	Flint, MI	09/20/07	09/19/07
62177	ASF Keystone, Inc. (USW)	Granite City, IL	09/21/07	09/20/07
62178	Alloc Inc (Comp)	Racine, WI	09/21/07	09/20/07
62179	Desa LLC (Comp)	Manchester, TN	09/21/07	09/20/07
62180	Cooper Standard Automotive (Comp)	Archbold, OH	09/21/07	09/20/07
62181	Louisiana Pacific Corporation (State)	Hines, OR	09/21/07	09/19/07
62182	Ideal Tool Inc. (Wkrs)	Meadville, PA	09/21/07	09/18/07
62183	Hartmann (Comp)	Lebanon, TN	09/21/07	09/19/07
62184	Mark Eyelet, Inc. (State)	Watertown, CT	09/21/07	09/20/07
62185	Halco (Wkrs)	Belle Vernon, PA	09/21/07	09/20/07
62186	TRW Automotive (AFLCIO)	Lebanon, TN	09/21/07	09/20/07
62187	Bock, USA Inc (State)	Monroe, CT	09/21/07	09/20/07
62188	Nortel (Wkrs)	Research Triangle Park, NC	09/21/07	09/12/07

[FR Doc. E7-19478 Filed 10-2-07; 8:45 am]

BILLING CODE 4510-FN-P

DEPARTMENT OF LABOR

Employment and Training Administration

[TA-W-61,601]

Intel Corporation, Fab 23, Colorado Springs, Colorado; Notice of Negative Determination on Reconsideration

On August 22, 2007, the Department issued an Affirmative Determination Regarding Application for Reconsideration applicable to workers and former workers of Intel Corporation, Fab 23, Colorado Springs, Colorado (the subject firm). The Department's Notice of affirmative determination was published in the **Federal Register** on August 29, 2007 (72 FR 49736). The subject workers produce silicon wafers.

The negative determination was based on the Department's findings that, during the relevant period, the subject firm's sales and production of silicon wafers increased, and the subject firm did not import or shift production of silicon wafers abroad. The Department's Notice of negative determination regarding the subject workers' eligibility to apply for Trade Adjustment Assistance (TAA) and Alternative Trade Adjustment Assistance (ATAA) was issued on June 15, 2007, and published in the **Federal Register** on June 28, 2007 (72 FR 35517).

The request for reconsideration makes three allegations.

First, the petitioner alleges that the Department misidentified the article produced at the subject firm ("Intel Fab23 does NOT manufacture Silicon Wafers, FAB23 manufactures electronic circuits called dies on a silicon wafer.

These dies are cut from the wafer and then packaged. At this time, the packaged dies are called 'chips' and sold. It should be noted, the manufactured wafer can be sold and the 'test and assembly' of the chip can take place elsewhere. There are three steps here, a) INTEL buys the bare silicon wafer from a supplier, b) Fab23 then manufactures the electronic circuit on the wafer called a die and c) then die is tested and assembly.") A corollary to this allegation is that the Department should have conducted a TAA investigation with a focus on chips instead of wafers.

Second, the petitioner alleges that the subject workers are eligible to apply for TAA due to a shift of production to Taiwan. The petitioner states that, in 2006, Intel Corporation (Intel) sold the "Hermon" line of chips to another company and that the subject firm agreed to produce "Hermon" chips for the buyer until the buyer's Taiwan facility could produce the "Hermon" chips. The petition asserts that because the subject firm is an "Agent Manufacturer" of the buyer, the buyer's decision to use Taiwanese chips should be construed as a shift of production from the subject firm to Taiwan.

Third, the petitioner alleges that the subject workers are eligible to apply for TAA as secondary workers. The petitioner stated, in part, that "Manufacturing Technicians of INTEL Fab 23 are likely secondary/down stream Employees" and that eligible secondary workers "include workers employed by supplier firms, downstream producers, and firms that provide contract services who are separated or threatened with separation if their separation is their separation is due to a loss of business with a firm where workers have been certified as

eligible to apply for trade adjustment assistance."

In order to determine whether the initial investigation focused on the wrong article, the Department carefully reviewed previously-submitted information, all the information provided in the request for reconsideration, new information provided by the subject firm, and information available in the public domain (such as the Internet).

The chip production process consists of three basic steps: first, prepare (purify and polish) a raw silicon wafer; second, process the wafer (add and expose layers of chemicals and circuitry onto the wafer) until engineered patterns of electrical passages (also called integrated circuits or chips) in the desired quantity are created; third, cut the circuit-laden wafer into individual dies and packaged (also called unit packaging).

Steps one and two are known as wafer fabrication. After wafer fabrication is complete, a quality control measure called a wafer sort may take place. Each wafer may carry hundreds or thousands of (usually) identical circuits, depending on the size of the circuitry and the diameter of the wafer.

According to the request for reconsideration, the article that exists at the end of step two is a manufactured wafer. According to the subject firm, the article that exists at the end of step two is a fabricated wafer.

At step three (also known as unit packaging), the fabricated wafer is cut into dies and processed into packaged chips (also called fabricated chips). After the wafer is cut into dies, each chip-bearing die is mounted on a small printed circuit board which will allow it to connect with other devices through solder ball connections. The chip/circuit-board unit is then coated with